

CAPABILITY FOR MCPCB:

ENGINEERING ITEM	CAPABILITY
SURFACE FINISHING	OSP, TIN/LEAD HASL, LEAD FREE HASL, IMM. GOLD
MATERIAL	TIMG-0, TIMG-1, TIMG-2
Thermal conductivity (W/mK)	TIMG-0(≤ 1.0), TIMG-1(≤ 1.5), TIMG-2(≤ 2.0)
LAYER COUNT	1
MAX. BOARD SIZE	1500MM*500MM
MIN. BOARD SIZE	5MM*5MM
MIN. TRACE WIDTH & SPACING	0.15MM
MAX. WARPAGE	$\leq 0.07\%$ (THICKNESS: 1.6MM, SIZE: 450MM*300MM)
FINISHED THICKNESS	0.4~4.0MM
COPPER WEIGHT	35UM~105UM
OUTLINE TOLERANCE	CNC: ± 0.10 MM; PUNCH: ± 0.15 MM
V-CUT ALIGNMENT	± 0.10 MM
CAPACITY	8000M2/MONTH
HOLE TOLERANCE	± 0.076 MM